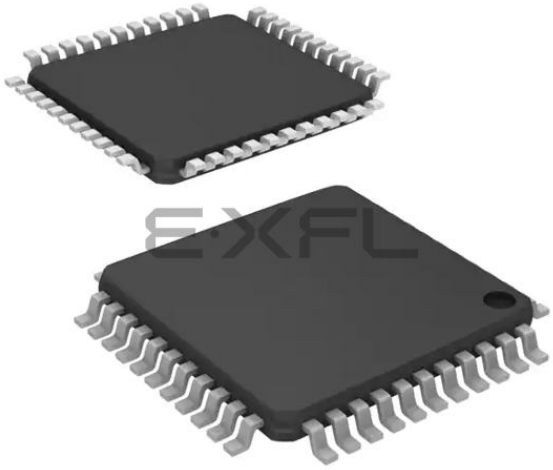

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx130f256dt-i-pt

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number[1]				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
SDA1	15	18	19	1	I/O	ST	Synchronous serial data input/output for I2C1
SCL2	4	7	2	24	I/O	ST	Synchronous serial clock input/output for I2C2
SDA2	3	6	1	23	I/O	ST	Synchronous serial data input/output for I2C2
TMS	19[2] 11[3]	22[2] 14[3]	25[2] 15[3]	12	I	ST	JTAG Test mode select pin
TCK	14	17	18	13	I	ST	JTAG test clock input pin
TDI	13	16	17	35	O	—	JTAG test data input pin
TDO	15	18	19	32	O	—	JTAG test data output pin
RTCC	4	7	2	24	O	ST	Real-Time Clock alarm output
CVREF-	28	3	34	20	I	Analog	Comparator Voltage Reference (low)
CVREF+	27	2	33	19	I	Analog	Comparator Voltage Reference (high)
CVREFOUT	22	25	28	14	O	Analog	Comparator Voltage Reference output
C1INA	4	7	2	24	I	Analog	Comparator Inputs
C1INB	3	6	1	23	I	Analog	
C1INC	2	5	36	22	I	Analog	
C1IND	1	4	35	21	I	Analog	
C2INA	2	5	36	22	I	Analog	
C2INB	1	4	35	21	I	Analog	
C2INC	4	7	2	24	I	Analog	
C2IND	3	6	1	23	I	Analog	
C3INA	23	26	29	15	I	Analog	
C3INB	22	25	28	14	I	Analog	
C3INC	27	2	33	19	I	Analog	
C3IND	1	4	35	21	I	Analog	
C1OUT	PPS	PPS	PPS	PPS	O	—	Comparator Outputs
C2OUT	PPS	PPS	PPS	PPS	O	—	
C3OUT	PPS	PPS	PPS	PPS	O	—	

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUs

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX 28/36/44-pin Family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 "Decoupling Capacitors"**)
- VCAP pin (see **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.7 "External Oscillator Pins"**)

The following pins may be required:

- VREF+/VREF- pins – used when external voltage reference for the ADC module is implemented

Note: The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

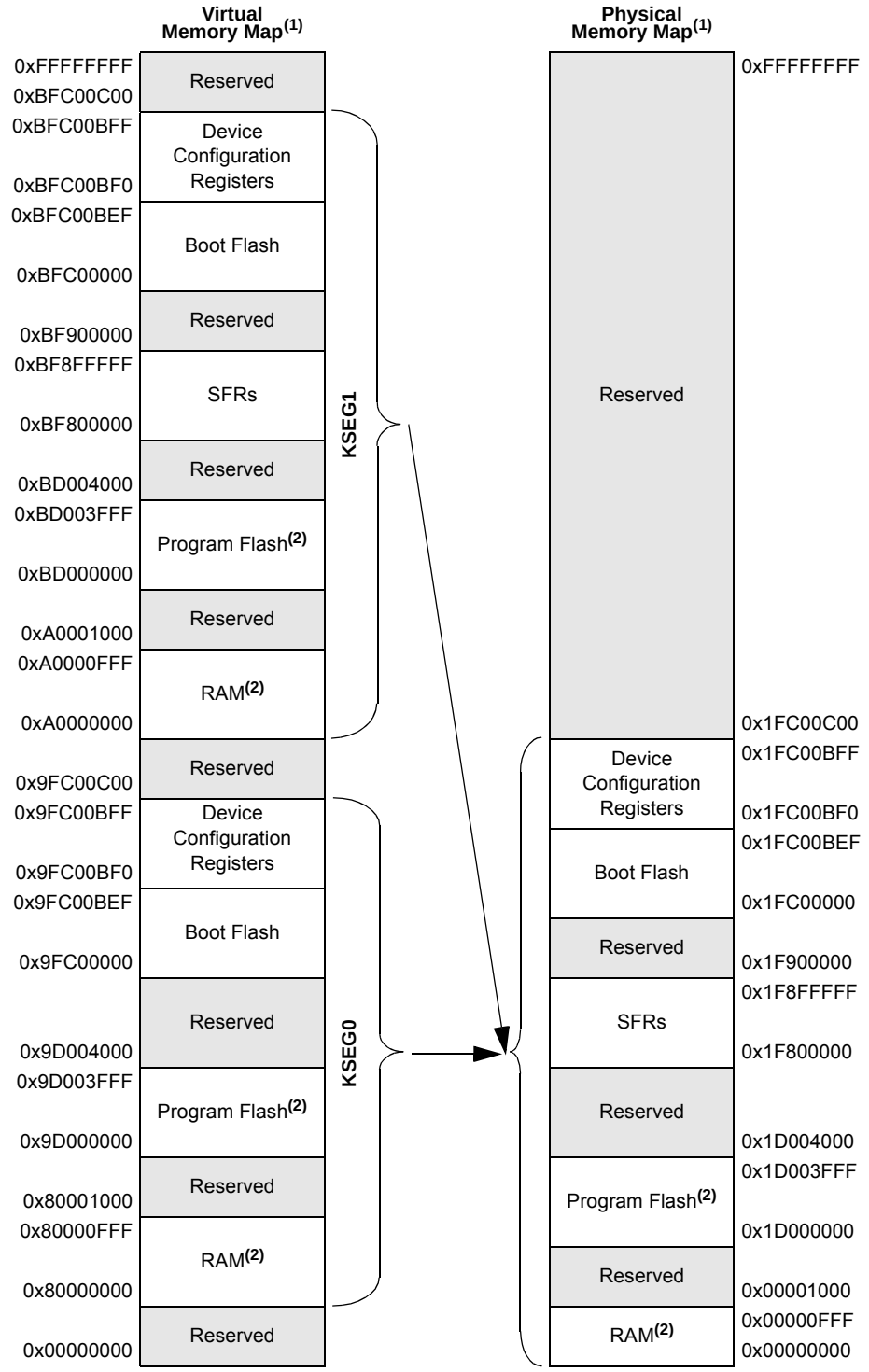
2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

FIGURE 4-1: MEMORY MAP ON RESET FOR PIC32MX110/210 DEVICES (4 KB RAM, 16 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

TABLE 7-1: INTERRUPT IRQ, VECTOR AND BIT LOCATION (CONTINUED)

Interrupt Source(1)	IRQ #	Vector #	Interrupt Bit Location				Persistent Interrupt
			Flag	Enable	Priority	Sub-priority	
U1E – UART1 Fault	39	32	IFS1<7>	IEC1<7>	IPC8<4:2>	IPC8<1:0>	Yes
U1RX – UART1 Receive Done	40	32	IFS1<8>	IEC1<8>	IPC8<4:2>	IPC8<1:0>	Yes
U1TX – UART1 Transfer Done	41	32	IFS1<9>	IEC1<9>	IPC8<4:2>	IPC8<1:0>	Yes
I2C1B – I2C1 Bus Collision Event	42	33	IFS1<10>	IEC1<10>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1S – I2C1 Slave Event	43	33	IFS1<11>	IEC1<11>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1M – I2C1 Master Event	44	33	IFS1<12>	IEC1<12>	IPC8<12:10>	IPC8<9:8>	Yes
CNA – PORTA Input Change Interrupt	45	34	IFS1<13>	IEC1<13>	IPC8<20:18>	IPC8<17:16>	Yes
CNB – PORTB Input Change Interrupt	46	34	IFS1<14>	IEC1<14>	IPC8<20:18>	IPC8<17:16>	Yes
CNC – PORTC Input Change Interrupt	47	34	IFS1<15>	IEC1<15>	IPC8<20:18>	IPC8<17:16>	Yes
PMP – Parallel Master Port	48	35	IFS1<16>	IEC1<16>	IPC8<28:26>	IPC8<25:24>	Yes
PMPE – Parallel Master Port Error	49	35	IFS1<17>	IEC1<17>	IPC8<28:26>	IPC8<25:24>	Yes
SPI2E – SPI2 Fault	50	36	IFS1<18>	IEC1<18>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2RX – SPI2 Receive Done	51	36	IFS1<19>	IEC1<19>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2TX – SPI2 Transfer Done	52	36	IFS1<20>	IEC1<20>	IPC9<4:2>	IPC9<1:0>	Yes
U2E – UART2 Error	53	37	IFS1<21>	IEC1<21>	IPC9<12:10>	IPC9<9:8>	Yes
U2RX – UART2 Receiver	54	37	IFS1<22>	IEC1<22>	IPC9<12:10>	IPC9<9:8>	Yes
U2TX – UART2 Transmitter	55	37	IFS1<23>	IEC1<23>	IPC9<12:10>	IPC9<9:8>	Yes
I2C2B – I2C2 Bus Collision Event	56	38	IFS1<24>	IEC1<24>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2S – I2C2 Slave Event	57	38	IFS1<25>	IEC1<25>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2M – I2C2 Master Event	58	38	IFS1<26>	IEC1<26>	IPC9<20:18>	IPC9<17:16>	Yes
CTMU – CTMU Event	59	39	IFS1<27>	IEC1<27>	IPC9<28:26>	IPC9<25:24>	Yes
DMA0 – DMA Channel 0	60	40	IFS1<28>	IEC1<28>	IPC10<4:2>	IPC10<1:0>	No
DMA1 – DMA Channel 1	61	41	IFS1<29>	IEC1<29>	IPC10<12:10>	IPC10<9:8>	No
DMA2 – DMA Channel 2	62	42	IFS1<30>	IEC1<30>	IPC10<20:18>	IPC10<17:16>	No
DMA3 – DMA Channel 3	63	43	IFS1<31>	IEC1<31>	IPC10<28:26>	IPC10<25:24>	No
Lowest Natural Order Priority							

Note 1: Not all interrupt sources are available on all devices. See **TABLE 1: "PIC32MX1XX 28/36/44-Pin General Purpose Family Features"** and **TABLE 2: "PIC32MX2XX 28/36/44-pin USB Family Features"** for the lists of available peripherals.

TABLE 9-3: DMA CHANNELS 0-3 REGISTER MAP (CONTINUED)

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3280	DCH2CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCPTR<15:0>																0000
3290	DCH2DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHPDAT<7:0>								0000
32A0	DCH3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHBUSY	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>		0000
32B0	DCH3ECON	31:16	—	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FF00
32C0	DCH3INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
32D0	DCH3SSA	31:16	CHSSA<31:0>																0000
		15:0																	0000
32E0	DCH3DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
32F0	DCH3SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSSIZ<15:0>																0000
3300	DCH3DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDSIZ<15:0>																0000
3310	DCH3SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSPTR<15:0>																0000
3320	DCH3DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDPTR<15:0>																0000
3330	DCH3CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCSIZ<15:0>																0000
3340	DCH3CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCPTR<15:0>																0000
3350	DCH3DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHPDAT<7:0>								0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

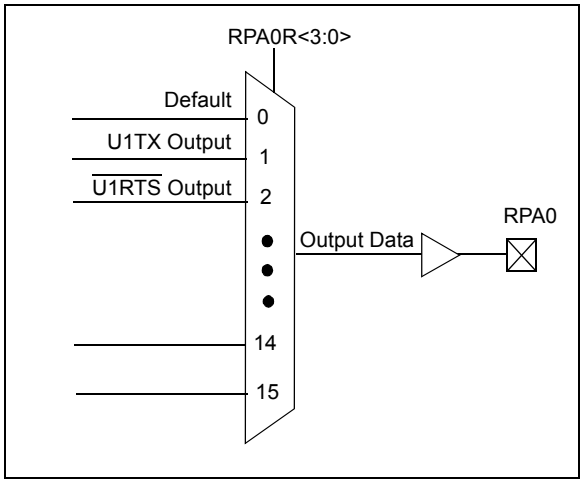
Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

11.3.5 OUTPUT MAPPING

In contrast to inputs, the outputs of the PPS options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPnR registers (Register 11-2) are used to control output mapping. Like the [*pin name*]R registers, each register contains sets of 4 bit fields. The value of the bit field corresponds to one of the peripherals, and that peripheral's output is mapped to the pin (see Table 11-2 and Figure 11-3).

A null output is associated with the output register reset value of '0'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 11-3: EXAMPLE OF MULTIPLEXING OF REMAPPABLE OUTPUT FOR RPA0



11.3.6 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. PIC32 devices include two features to prevent alterations to the peripheral map:

- Control register lock sequence
- Configuration bit select lock

11.3.6.1 Control Register Lock Sequence

Under normal operation, writes to the RPnR and [*pin name*]R registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the Configuration bit, IOLOCK (CFGCON<13>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear the IOLOCK bit, an unlock sequence must be executed. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

11.3.6.2 Configuration Bit Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPnR and [*pin name*]R registers. The Configuration bit, IOL1WAY (DEVCFG3<29>), blocks the IOLOCK bit from being cleared after it has been set once. If IOLOCK remains set, the register unlock procedure does not execute, and the PPS control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session.

NOTES:

18.1 I2C Control Registers

TABLE 18-1: I2C1 AND I2C2 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5000	I2C1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5010	I2C1STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
5020	I2C1ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Register										0000
5030	I2C1MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Mask Register										0000
5040	I2C1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	Baud Rate Generator Register												0000
5050	I2C1TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Transmit Register								0000
5060	I2C1RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Receive Register								0000
5100	I2C2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5110	I2C2STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
5120	I2C2ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Register										0000
5130	I2C2MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Mask Register										0000
5140	I2C2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	Baud Rate Generator Register												0000
5150	I2C2TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Transmit Register								0000
5160	I2C2RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Receive Register								0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table except I2CxRCV have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

NOTES:

REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER (CONTINUED)

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits(2)

11111111 = Alarm will trigger 256 times
•
•
•
00000000 = Alarm will trigger one time
The counter decrements on any alarm event. The counter only rolls over from 0x00 to 0xFF if CHIME = 1.

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.

2: This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note:	This register is reset only on a Power-on Reset (POR).

REGISTER 22-2: AD1CON2: ADC CONTROL REGISTER 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0	U-0
	VCFG<2:0>			OFFCAL	—	CSCNA	—	—
7:0	R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BUFS	—	SMPI<3:0>				BUFM	ALTS

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-13 **VCFG<2:0>:** Voltage Reference Configuration bits

	VREFH	VREFL
000	AVDD	AVss
001	External VREF+ pin	AVSS
010	AVDD	External VREF- pin
011	External VREF+ pin	External VREF- pin
1xx	AVDD	AVSS

bit 12 **OFFCAL:** Input Offset Calibration Mode Select bit
1 = Enable Offset Calibration mode
Positive and negative inputs of the sample and hold amplifier are connected to VREFL
0 = Disable Offset Calibration mode
The inputs to the sample and hold amplifier are controlled by AD1CHS or AD1CSSL

bit 11 **Unimplemented:** Read as '0'

bit 10 **CSCNA:** Input Scan Select bit
1 = Scan inputs
0 = Do not scan inputs

bit 9-8 **Unimplemented:** Read as '0'

bit 7 **BUFS:** Buffer Fill Status bit
Only valid when BUFM = 1.
1 = ADC is currently filling buffer 0x8-0xF, user should access data in 0x0-0x7
0 = ADC is currently filling buffer 0x0-0x7, user should access data in 0x8-0xF

bit 6 **Unimplemented:** Read as '0'

bit 5-2 **SMPI<3:0>:** Sample/Convert Sequences Per Interrupt Selection bits
1111 = Interrupts at the completion of conversion for each 16th sample/convert sequence
1110 = Interrupts at the completion of conversion for each 15th sample/convert sequence
•
•
•
0001 = Interrupts at the completion of conversion for each 2nd sample/convert sequence
0000 = Interrupts at the completion of conversion for each sample/convert sequence

bit 1 **BUFM:** ADC Result Buffer Mode Select bit
1 = Buffer configured as two 8-word buffers, ADC1BUF7-ADC1BUF0, ADC1BUFF-ADCBUF8
0 = Buffer configured as one 16-word buffer ADC1BUFF-ADC1BUF0

bit 0 **ALTS:** Alternate Input Sample Mode Select bit
1 = Uses Sample A input multiplexer settings for first sample, then alternates between Sample B and Sample A input multiplexer settings for all subsequent samples
0 = Always use Sample A input multiplexer settings

REGISTER 22-4: AD1CHS: ADC INPUT SELECT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	CH0NB	—	—	—	CH0SB<3:0>			
23:16	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	CH0NA	—	—	—	CH0SA<3:0>			
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **CH0NB:** Negative Input Select bit for Sample B
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VREFL

bit 30-28 **Unimplemented:** Read as '0'

bit 27-24 **CH0SB<3:0>:** Positive Input Select bits for Sample B
1111 = Channel 0 positive input is Open(1)
1110 = Channel 0 positive input is IVREF(2)
1101 = Channel 0 positive input is CTMU temperature sensor (CTMUT)(3)
1100 = Channel 0 positive input is AN12(4)
•
•
•
0001 = Channel 0 positive input is AN1
0000 = Channel 0 positive input is AN0

bit 23 **CH0NA:** Negative Input Select bit for Sample A Multiplexer Setting(2)
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VREFL

bit 22-20 **Unimplemented:** Read as '0'

bit 19-16 **CH0SA<3:0>:** Positive Input Select bits for Sample A Multiplexer Setting
1111 = Channel 0 positive input is Open(1)
1110 = Channel 0 positive input is IVREF(2)
1101 = Channel 0 positive input is CTMU temperature (CTMUT)(3)
1100 = Channel 0 positive input is AN12(4)
•
•
•
0001 = Channel 0 positive input is AN1
0000 = Channel 0 positive input is AN0

bit 15-0 **Unimplemented:** Read as '0'

Note 1: This selection is only used with CTMU capacitive and time measurement.
2: See **Section 24.0 "Comparator Voltage Reference (CVREF)"** for more information.
3: See **Section 25.0 "Charge Time Measurement Unit (CTMU)"** for more information.
4: AN12 is only available on 44-pin devices. AN6-AN8 are not available on 28-pin devices.

30.1 DC Characteristics

TABLE 30-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)(1)	Temp. Range (in °C)	Max. Frequency
			PIC32MX1XX/2XX 28/36/44-pin Family
DC5	2.3-3.6V	-40°C to +85°C	40 MHz
DC5b	2.3-3.6V	-40°C to +105°C	40 MHz

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 30-11 for BOR values.

TABLE 30-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
V-temp Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – S IOH) I/O Pin Power Dissipation: I/O = S (({VDD – VOH} x IOH) + S (VOL x IOL))	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 30-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 28-pin SSOP	θJA	71	—	°C/W	**1**
Package Thermal Resistance, 28-pin SOIC	θJA	50	—	°C/W	**1**
Package Thermal Resistance, 28-pin SPDIP	θJA	42	—	°C/W	**1**
Package Thermal Resistance, 28-pin QFN	θJA	35	—	°C/W	**1**
Package Thermal Resistance, 36-pin VTLA	θJA	31	—	°C/W	**1**
Package Thermal Resistance, 44-pin QFN	θJA	32	—	°C/W	**1**
Package Thermal Resistance, 44-pin TQFP	θJA	45	—	°C/W	**1**
Package Thermal Resistance, 44-pin VTLA	θJA	30	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 30-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O Pins with PMP	VSS	—	0.15 VDD	V	
		I/O Pins	VSS	—	0.2 VDD	V	
DI18		SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled **(Note 4)**
DI19		SDAx, SCLx	VSS	—	0.8	V	SMBus enabled **(Note 4)**
	VIH	**Input High Voltage**					
DI20		I/O Pins not 5V-tolerant(5)	0.65 VDD	—	VDD	V	**(Note 4,6)**
		I/O Pins 5V-tolerant with PMP(5)	0.25 VDD + 0.8V	—	5.5	V	**(Note 4,6)**
		I/O Pins 5V-tolerant(5)	0.65 VDD	—	5.5	V	
DI28		SDAx, SCLx	0.65 VDD	—	5.5	V	SMBus disabled **(Note 4,6)**
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤ VPIN ≤ 5.5 **(Note 4,6)**
DI30	ICNPU	**Change Notification Pull-up Current**	—	—	-50	µA	VDD = 3.3V, VPIN = VSS **(Note 3,6)**
DI31	ICNPD	**Change Notification Pull-down Current(4)**	—	—	-50	µA	VDD = 3.3V, VPIN = VDD
	IIL	**Input Leakage Current (Note 3)**					
DI50		I/O Ports	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{\text{MCLR}}$(2)	—	—	±1	µA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **"Pin Diagrams"** section for the 5V-tolerant pins.

6: The VIH specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic "high" internally to the PIC32 device, provided that the external load does not exceed the minimum value of ICNPU. For External "input" logic inputs that require a pull-up source, to guarantee the minimum VIH of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

30.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX1XX/2XX 28/36/44-pin Family AC characteristics and timing parameters.

FIGURE 30-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

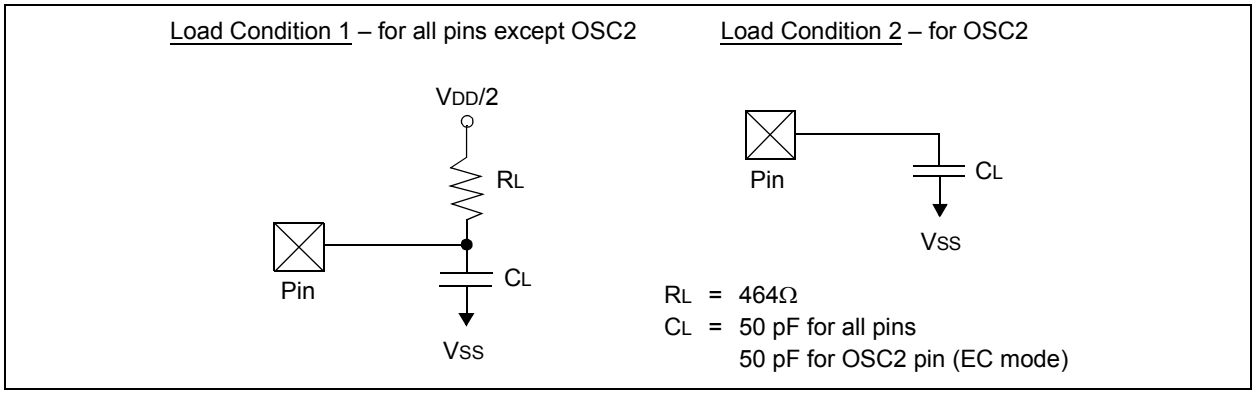


TABLE 30-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
DO56	CIO	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C mode

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-2: EXTERNAL CLOCK TIMING

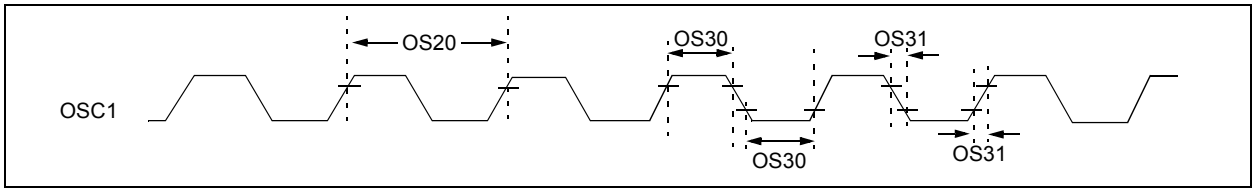
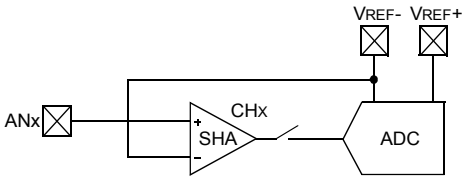
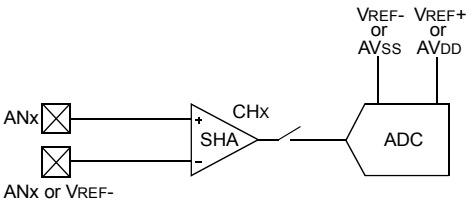


TABLE 30-35: 10-BIT CONVERSION RATE PARAMETERS

AC CHARACTERISTICS(2)			Standard Operating Conditions (see Note 3): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
ADC Speed	**TAD Min.**	**Sampling Time Min.**	**RS Max.**	**VDD**	**ADC Channels Configuration**
1 Msps to 400 ksps(1)	65 ns	132 ns	500Ω	3.0V to 3.6V	
Up to 400 ksps	200 ns	200 ns	5.0 kΩ	2.5V to 3.6V	

Note 1: External VREF- and VREF+ pins must be used for correct operation.

2: These parameters are characterized, but not tested in manufacturing.

3: The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

TABLE 30-39: PARALLEL MASTER PORT WRITE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
PM11	TWR	PMWR Pulse Width	—	1 TPB	—	—	—
PM12	TDVSU	Data Out Valid before PMWR or PMENB goes Inactive (data setup time)	—	2 TPB	—	—	—
PM13	TDVHOLD	PMWR or PMEMB Invalid to Data Out Invalid (data hold time)	—	1 TPB	—	—	—

Note 1: These parameters are characterized, but not tested in manufacturing.

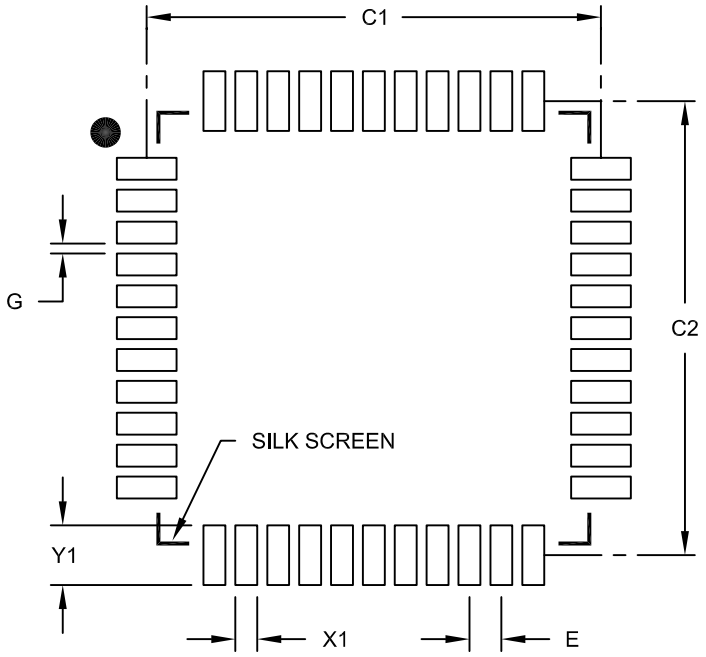
TABLE 30-40: OTG ELECTRICAL SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
USB313	VUSB3V3	USB Voltage	3.0	—	3.6	V	Voltage on VUSB3V3 must be in this range for proper USB operation
USB315	VILUSB	Input Low Voltage for USB Buffer	—	—	0.8	V	—
USB316	VIHUSB	Input High Voltage for USB Buffer	2.0	—	—	V	—
USB318	VDIFS	Differential Input Sensitivity	—	—	0.2	V	The difference between D+ and D- must exceed this value while VCM is met
USB319	VCM	Differential Common Mode Range	0.8	—	2.5	V	—
USB320	ZOUT	Driver Output Impedance	28.0	—	44.0	Ω	—
USB321	VOL	Voltage Output Low	0.0	—	0.3	V	1.425 kΩ load connected to VUSB3V3
USB322	VOH	Voltage Output High	2.8	—	3.6	V	1.425 kΩ load connected to ground

Note 1: These parameters are characterized, but not tested in manufacturing.

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

Revision D (February 2012)

All occurrences of VUSB were changed to: VUSB3V3. In addition, text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in Table A-3.

TABLE A-3: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog**"**	Corrected a part number error in all pin diagrams. Updated the DMA Channels (Programmable/Dedicated) column in the PIC32MX1XX General Purpose Family Features (see Table 1).
1.0 "Device Overview"	Added the TQFP and VTLA packages to the 44-pin column heading and updated the pin numbers for the SCL1, SCL2, SDA1, and SDA2 pins in the Pinout I/O Descriptions (see Table 1-1).
7.0 "Interrupt Controller"	Updated the Note that follows the features. Updated the Interrupt Controller Block Diagram (see Figure 7-1).
29.0 "Electrical Characteristics"	Updated the Maximum values for parameters DC20-DC24, and the Minimum value for parameter DC21 in the Operating Current (IDD) DC Characteristics (see Table 29-5). Updated all Minimum and Maximum values for the Idle Current (IIDLE) DC Characteristics (see Table 29-6). Updated the Maximum values for parameters DC40k, DC40l, DC40n, and DC40m in the Power-down Current (IPD) DC Characteristics (see Table 29-7). Changed the minimum clock period for SCKx from 40 ns to 50 ns in Note 3 of the SPIx Master and Slave Mode Timing Requirements (see Table 29-26 through Table 29-29).
30.0 "DC and AC Device Characteristics Graphs"	Updated the Typical IIDLE Current @ VDD = 3.3V graph (see Figure 30-5).

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